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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/086,875	03/04/2002	Masaki Watanabe	50090-465	2413
7590 12/01/2004			EXAMINER	
McDermott, Will & Emery			BEREZNY, NEMA O	
600 13th Street, N.W. Washington, DC 20005-3096			ART UNIT	PAPER NUMBER
ζ,			2813	
		DATE MAILED: 12/01/2004		

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)			
	10/086,875	WATANABE, MASAKI			
Office Action Summary	Examiner	Art Unit			
	Nema O Berezny	2813			
The MAILING DATE of this communication appears on the cover sheet with the correspondence address Period for Reply					
A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely. - If NO period for reply sepecified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication. - Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).					
Status					
1)⊠ Responsive to communication(s) filed on <u>17 June 2004</u> .					
2a) This action is FINAL . 2b) ⊠ This					
	· -				
Disposition of Claims					
 4) Claim(s) 13-18 is/are pending in the application. 4a) Of the above claim(s) is/are withdrawn from consideration. 5) Claim(s) is/are allowed. 6) Claim(s) 13-18 is/are rejected. 7) Claim(s) is/are objected to. 8) Claim(s) are subject to restriction and/or election requirement. 					
Application Papers					
 9) The specification is objected to by the Examiner. 10) The drawing(s) filed on <u>04 March 2002</u> is/are: a) accepted or b) objected to by the Examiner. Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a). Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d). 11) The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152. 					
Priority under 35 U.S.C. § 119					
 12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f). a) All b) Some * c) None of: 1. Certified copies of the priority documents have been received. 2. Certified copies of the priority documents have been received in Application No. 09/484,024. 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)). * See the attached detailed Office action for a list of the certified copies not received. 					
Attachment(s) 1) Notice of References Cited (PTO-892)	4) Interview Summary				
 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08 Paper No(s)/Mail Date 	Paper No(s)/Mail Da 5) Notice of Informal P 6) Other:	ate Patent Application (PTO-152)			

Application/Control Number: 10/086,875

Art Unit: 2813

DETAILED ACTION

This Office Action is in response to Applicant's Response filed 6-17-04, which has been entered and considered. Claims 13-18 are currently pending.

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

Claims 13-18 are rejected under 35 U.S.C. 102(e) as being anticipated by Jacobs (6,294,407). Jacobs discloses a method for manufacturing a package for accommodating electronic parts, comprising the steps of: forming a buildup substrate having: a core substrate (Fig.10 el.130); a power source (el. P) and/or a ground layer (el. G) on said core substrate, a buildup interconnecting layer (el.1010), and signal lines (el.1016) on said buildup interconnecting layer; adhering a stiffener (el.110) to said signal lines with a conductive adhesive layer (el.1014b) using a conductive adhesive; and forming a grounding plane (el. G) using said stiffener and said buildup substrate wherein said conductive adhesive layer is formed on said signal lines [claim 13]. Jacobs also discloses fixing said conductive adhesive layer at a grounding potential (el.1014b to el.1016 to el.132 to el. G) [claim 14]; providing pads (no # - inherent)

Application/Control Number: 10/086,875

Art Unit: 2813

connected to said grounding plane on the surface of said buildup substrate as well as electrically connecting said pads to said conductive adhesive layer (el. G to el.132 to el.1016 to el.1014b) [claim 16]; and providing a plurality of ground connecting pads (Fig.1 el.112a) on said buildup interconnecting layer; and connecting said conductive adhesive layer having mainly a conductive adhesive to said plurality of ground connecting pads (col.5 line 64 – col.6 line 2) [claims 15, 17, 18].

Response to Arguments

Applicant's arguments, see p.2 para.3, filed 6-17-04, with respect to the rejection(s)of claim(s) 13-18 under Shimada (5,631,402) have been fully considered and are persuasive. Therefore, the rejection has been withdrawn. However, upon further consideration, a new ground(s) of rejection is made in view of Jacobs (6,294,407).

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Nema O Berezny whose telephone number is (571) 272-1686. The examiner can normally be reached on M-F 9-5:30.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Carl Whitehead, Jr. can be reached on (571) 272-1702. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Application/Control Number: 10/086,875 Page 4

Art Unit: 2813

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

NB

V Jema Berezny